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Part Number: [0541323362](#)
Status: **Active**
Overview: [ffc_fpc_smt](#)
Description: 0.50mm (.020") Pitch FFC/FPC Connector, Right Angle, SMT, ZIF, Bottom Contact Style, 33 Circuits, 0.1µm (4µ") Gold (Au) Contact Plating

Documents:

[3D Model](#) [Product Specification PS-54132-061 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

UL E29179

General

Product Family FFC/FPC Connectors
 Series [54132](#)
 Overview [ffc_fpc_smt](#)
 Product Name N/A

Physical

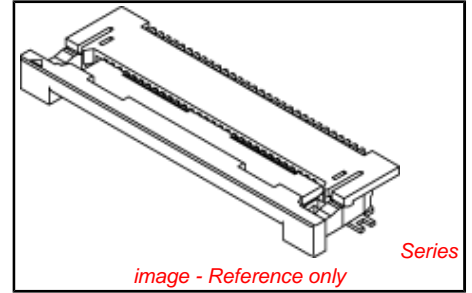
Circuits (Loaded) 33
 Color - Resin Black, Natural
 Contact Position Bottom
 Durability (mating cycles max) 20
 Entry Angle 90° Angle
 Flammability 94V-0
 Mated Height (in) 0.079 In
 Mated Height (mm) 2.00 mm
 Material - Metal Phosphor Bronze
 Material - Plating Mating Gold
 Material - Plating Termination Gold
 Material - Resin High Temperature Thermoplastic
 Number of Rows 1
 Orientation Right Angle
 PCB Locator No
 PCB Retention Yes
 Packaging Type Embossed Tape on Reel
 Pitch - Mating Interface (in) 0.020 In
 Pitch - Mating Interface (mm) 0.50 mm
 Plating min: Mating (µin) 4
 Plating min: Mating (µm) 0.1
 Plating min: Termination (µin) 2
 Plating min: Termination (µm) 0.05
 Polarized to PCB Yes
 Stackable No
 Surface Mount Compatible (SMC) N/A
 Temperature Range - Operating -20°C to +85°C
 Termination Interface: Style Surface Mount
 Wire/Cable Type FFC/FPC

Electrical

Current - Maximum per Contact 0.5A
 Voltage - Maximum 50V

Material Info

Reference - Drawing Numbers



EU RoHS
ELV and RoHS
Compliant
REACH SVHC
 Not Reviewed
Halogen-Free
Status
Not Halogen-Free

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com
 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series
[54132Series](#)

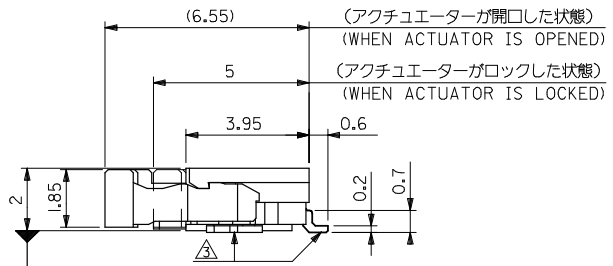
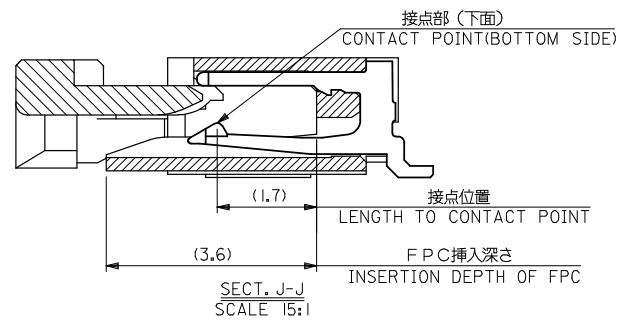
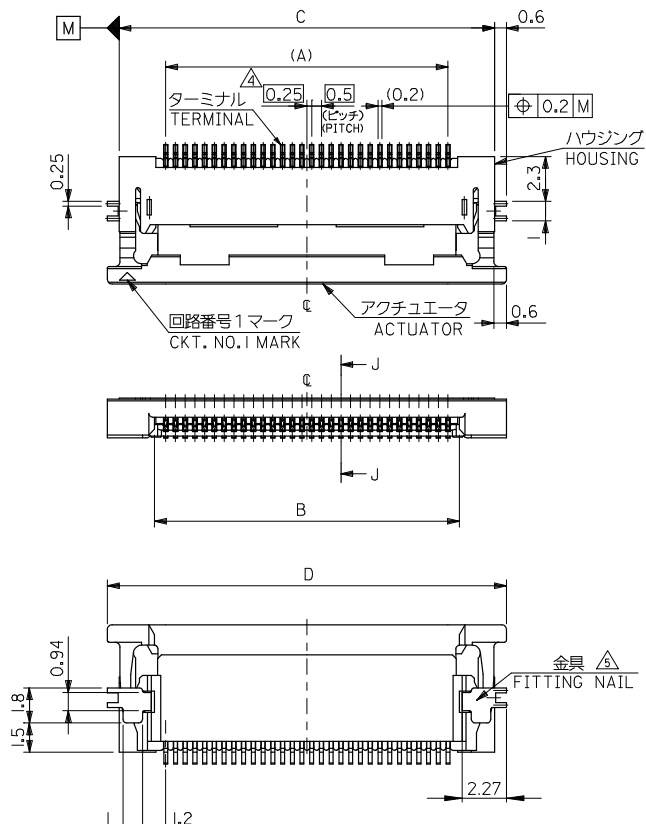
Product Specification
Sales Drawing

PS-54132-061, RPS-54132-071, RPS-54132-076
SD-54132-064

This document was generated on 06/07/2010

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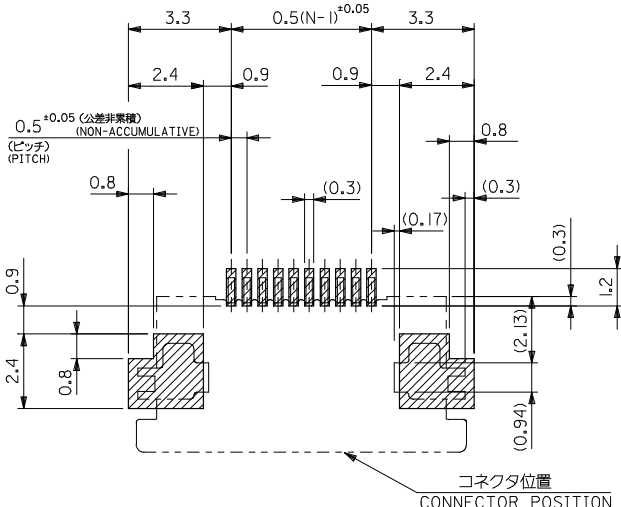
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27.0	25.8	22.15	21.0	54132-4362	54132-4368	43
25.5	24.3	20.65	19.5	54132-4062	54132-4068	40
24.5	23.3	19.65	18.5	54132-3862	54132-3868	38
23.5	22.3	18.65	17.5	54132-3662	54132-3668	36
23.0	21.8	18.15	17.0	54132-3562	54132-3568	35
22.5	21.3	17.65	16.5	54132-3462	54132-3468	34
22.0	20.8	17.15	16.0	54132-3362	54132-3368	33
21.5	20.3	16.65	15.5	54132-3262	54132-3268	32
20.5	19.3	15.65	14.5	54132-3062	54132-3068	30

REVISED EC NO: J2008-4308 DRAWN BY: 2008/06/27 CHYKD:THARYAMA APPR:NIKIITA 2008/06/30 2008/06/30	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY M.UMEDA	DATE 2004/09/27	TITLE 0.5 FPC CONN. HSG ASSY BTM CONTACT GOLD PLATING -LEAD FREE-(NI-BARRIER)		
	10 OVER 30 UNDER	±0.25	CHECKED BY K.TOYODA	DATE 2004/09/27	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY N.UKIITA	DATE 2004/09/27	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-54132-064	SHEET NO. 1 OF 4
ANGULAR ±3°		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

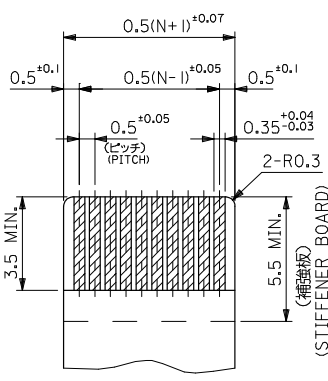
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Rev. E 2006/04/15

EN-02JA(021)

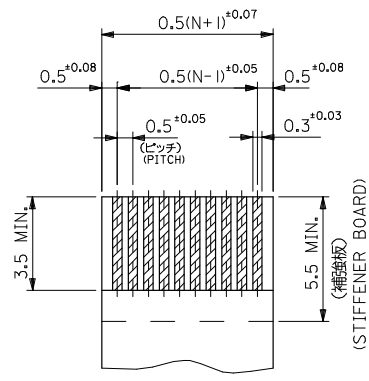
10 9 8 7 6 5 4 3 2 1



参考基板レイアウト
RECOMMENDED PC BOARD PATTERN DIMENSION (REF.)
(マウント面)
(MOUNTING SIDE)



適合FPC推奨寸法
APPLICABLE FPC RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3^{+0.03})
(THICKNESS: 0.3^{+0.03})



適合FFC推奨寸法
APPLICABLE FFC RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3^{+0.03})
(THICKNESS: 0.3^{+0.03})

注記
NOTES

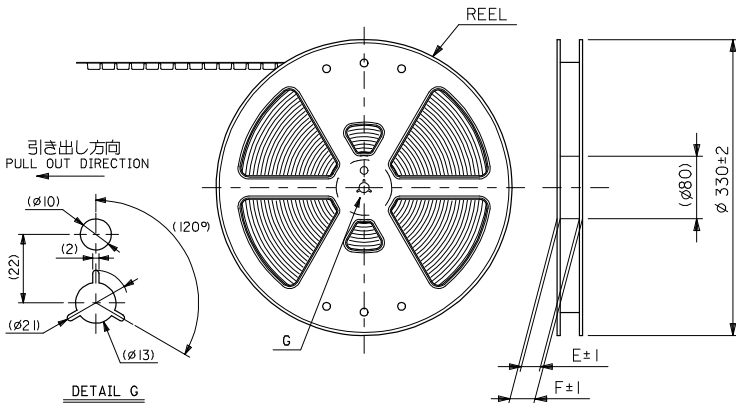
- 使用材料 MATERIAL : 46ナイロン, UL94V-0
ハウジング HOUSING : 46NYLON
アクチュエーター ACTUATOR : PPS, UL94V-0
ターミナル TERMINAL : 金メッキ CONTACT部 0.1 MICRO METER MIN. テール部 0.05 MICRO METER MIN. ニッケル下地 1.0 MICRO METER MIN.
FITTING NAIL : リン青銅 (t=0.2), 鍍メッキ 1.0~3.0 MICRO METER MIN. ニッケル下地 1.0~3.0 MICRO METER MIN. PHOS-BRO.TIN-PLATE 1.0~3.0 MICRO METER MIN. OVER NICKEL 1.0~3.0 MICRO METER MIN.

- エンボステープ梱包時は、アクチュエーターがロックした状態とする。
IN THE PACKAGE, ACTUATOR OF PART NO.54132-**69 SHOULD BE LOCKED.
- ソルダータール半田付け面のスレ量、及び金具半田付け面のスレ量は、基準面 田に対し上方向0.1MAX.、下方向0.15MAX.とする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAIL FROM 田 UPPER DIRECTION: 0.1 MAX., LOWER DIRECTION: 0.15 MAX.
- 偶数個に適用
APPLY FOR EVEN CIRCUIT.
- パターンはくり止め用金具
FITTING NAIL FOR PREVENTION OF PEELING OF P.C.B. PATTERN.
- 本製品は54132-**61に対するニッケルバリアである。
THIS PRODUCT IS Ni-Barrier OF 54132-**61.

- FPC/FFCについて:
打抜き方向は導体側から補強板側を推奨いたします。
導体部については数銅箔35マイクロメートルまたは50マイクロメートル
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED CONDUCTOR SPEC:
THICKNESS OF SOFT COPPER FOIL : 35 micrometer or 50 micrometer
- FPCについて:
補強フィルム材質はポリイミドを推奨いたします。
接着剤は熱硬化接着剤を推奨いたします。
RECOMMENDED MATERIAL:
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

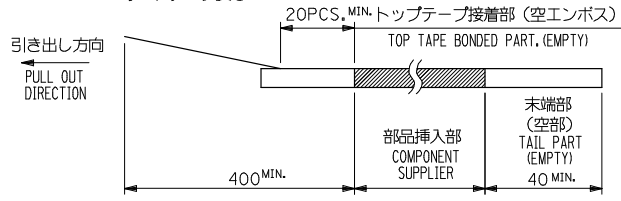
REVISED EC NO: J2008-4308 DRAWN: MABELI 2008/06/30 CHKD: THARYAMA APPR: NIKITA 2008/06/30	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY M.UMEDA	DATE 2004/09/27	TITLE 0.5 FPC CONN. HSG ASSY BTM CONTACT GOLD PLATING -LEAD FREE-(NI-BARRIER)		
	10 OVER 30 UNDER	±0.25	CHECKED BY K. TOYODA	DATE 2004/09/27	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY N. UKITA	DATE 2004/09/27	MATERIAL NO. SEE SHEET 1	DOCUMENT NO. SD-54132-064	SHEET NO. 2 OF 4
ANGULAR	±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					
SIZE A THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

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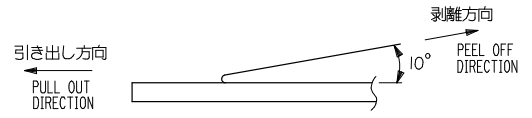


NOTES

- 1. 梱包数量：1500個/リール
NUMBER OF CONNECTORS : 1500PCS/REEL
- 2. リードテープ長さ LEAD TAPE LENGTH



- 3. トップテープの剥離強度：0.1N ~ 1.3N(10gf ~ 130gf)
(剥離方向は下図参照)
尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)
PEELING OFF FORCE OF TOP TAPE : 0.1N ~ 1.3N(10gf ~ 130gf)
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
PEEL OFF SHOULD NOT BE ALLOWED ,DURING TRANSPORTATION.



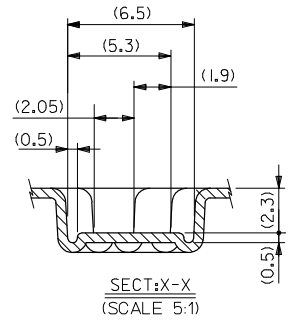
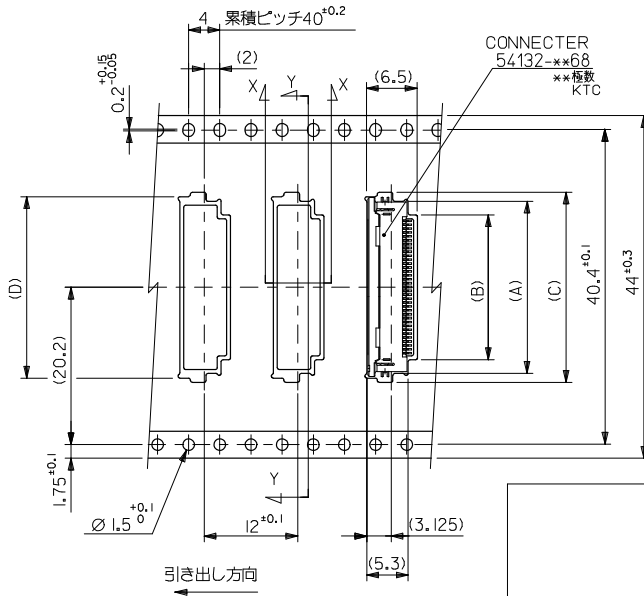
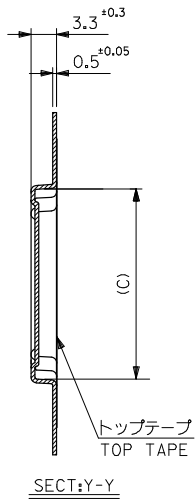
- 5. 材料 キャリアテープ：ポリプロピレン (PP)
トップテープ：PET, PE, PEF
リール：ポリスチレン (PS) <リサイクル材を含む>

MATERIAL CARRIER TAPE:POLYPROPYLENE
TOP TAPE:PET,PE,PEF
REEL:POLYSTYRENE(PS)
<RECYCLE MATERIAL CONTAINED>

- 6. 本製品は54132-*61に対するニッケルバリア品である。
THIS PRODUCT IS Ni-Barrier OF 54132-*61.

REVISED EC NO: J2008-4308 DRAWN BY: M. UMEDA CHECKED BY: K. TOYODA APPROVED BY: N. UKITA DATE: 2008/06/27 DATE: 2008/06/30 DATE: 2008/06/30	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
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	30 OVER	±---	APPROVED BY N. UKITA	DATE 2004/09/27	DOCUMENT NO. SD-54132-064		
ANGULAR	±--- °	MATERIAL NO. SEE SHEET 4		SHEET NO. 3 OF 4		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	

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44	49.4	45.4	30.8	31.9	26.1	29.6	54132-5062	50		
			28.3	29.4	23.6	27.1	54132-4562	45		
			27.3	28.4	22.6	26.1	54132-4362	43		
			25.8	26.9	21.1	24.6	54132-4062	40		
			24.8	25.9	20.1	23.6	54132-3862	38		
			23.8	24.9	19.1	22.6	54132-3662	36		
			23.3	24.4	18.6	22.1	54132-3562	35		
			22.8	23.9	18.1	21.6	54132-3462	34		
			22.3	23.4	17.6	21.1	54132-3362	33		
			21.8	22.9	17.1	20.6	54132-3262	32		
20.8	21.9	16.1	19.6	54132-3062	30					
キャリアテープ幅 CARRIER TAPE WIDTH			F	E	D	C	B	A	MATERIAL NO. (EMBOSS PKG)	CKT.

REVISED EC NO: J2008-4308 DRAWN BY: M. UMEDA 2008/06/27 CHECKED BY: CHYKO:THARYAMA 2008/06/30 APPROVED BY: APPR:NIKIITA 2008/06/30 DESCRIPTION:	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
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	30 OVER	±---	APPROVED BY M. UMEDA	DATE 2004/09/27	DOCUMENT NO. SD-54132-064		SHEET NO. 4 OF 4	
	ANGULAR ±--- °		MATERIAL NO. SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS								